

Inventors: Teck Kheng Lee
Filed: April 22, 2004
Attorney Docket No. 4974.1US

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METHODS FOR ASSEMBLY AND PACKAGING OF FLIP
CHIP CONFIGURED DICE WITH INTERPOSER

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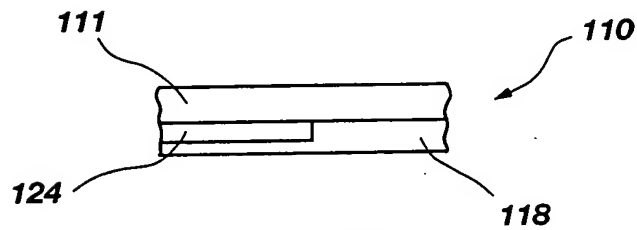


Fig. 4A

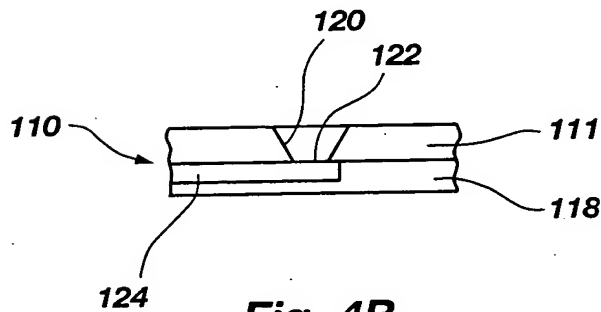


Fig. 4B

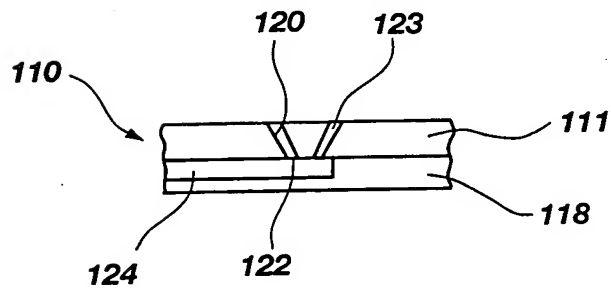


Fig. 4C

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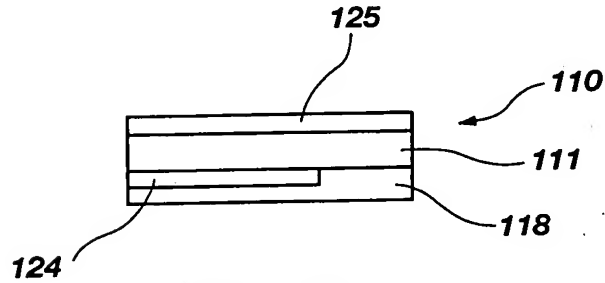


Fig. 5A

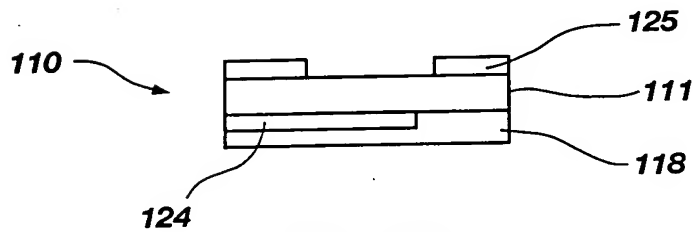


Fig. 5B

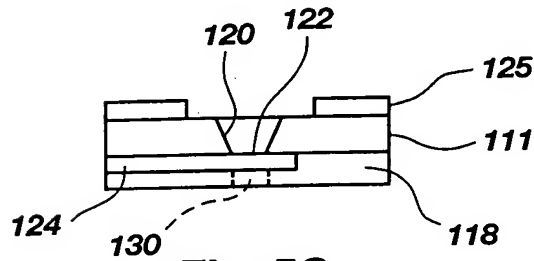


Fig. 5C

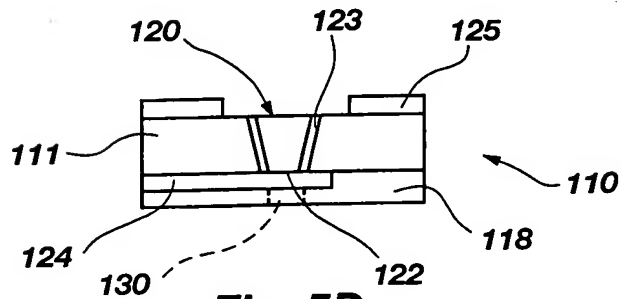


Fig. 5D

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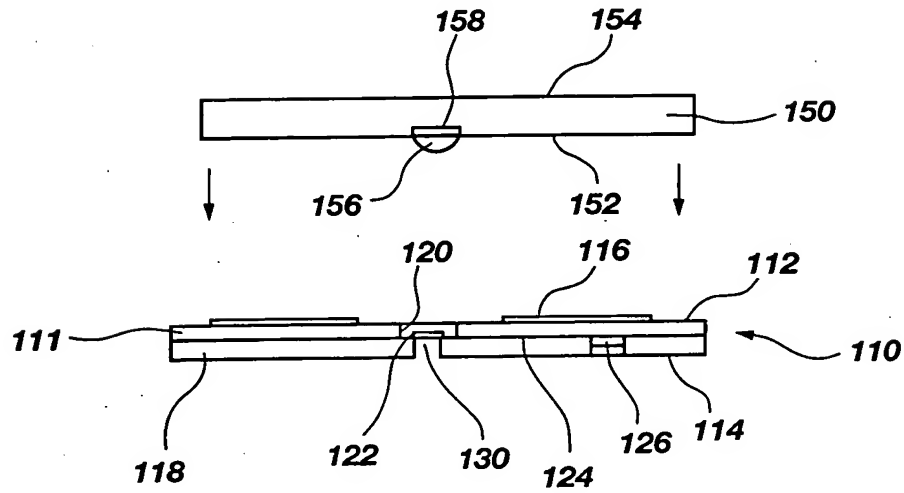


Fig. 6A

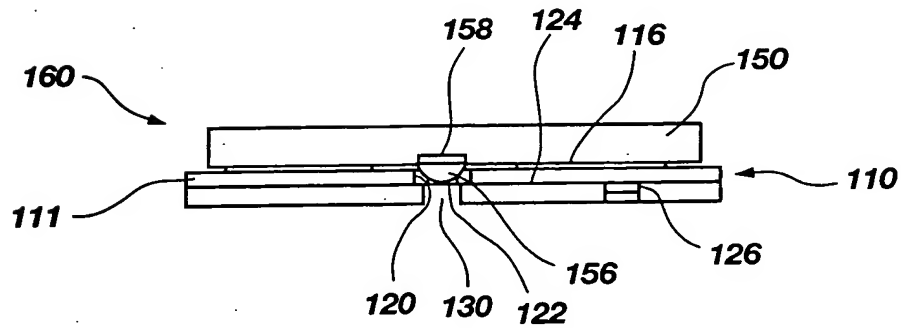


Fig. 6B

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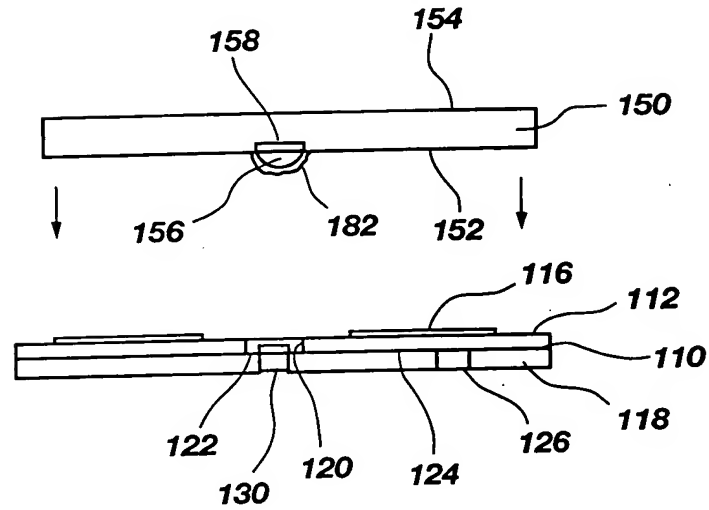


Fig. 7A

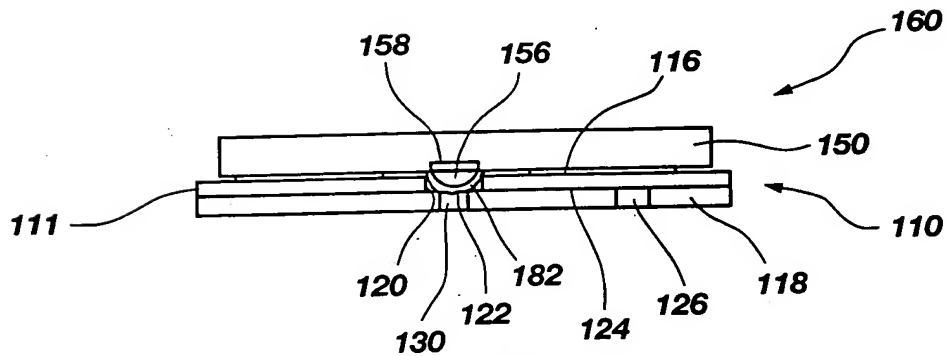
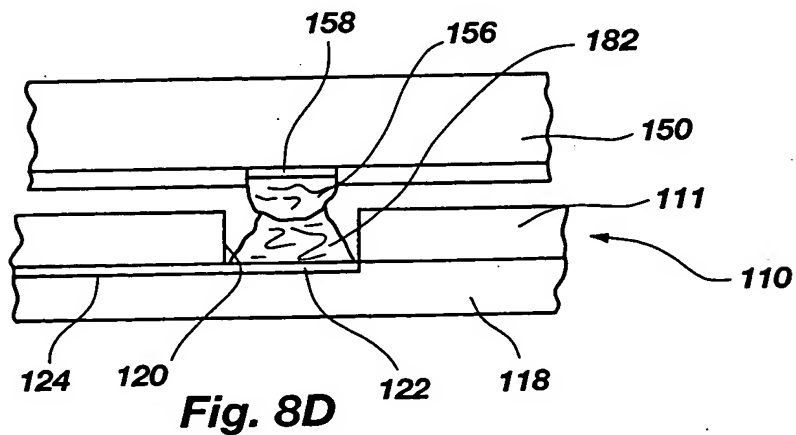
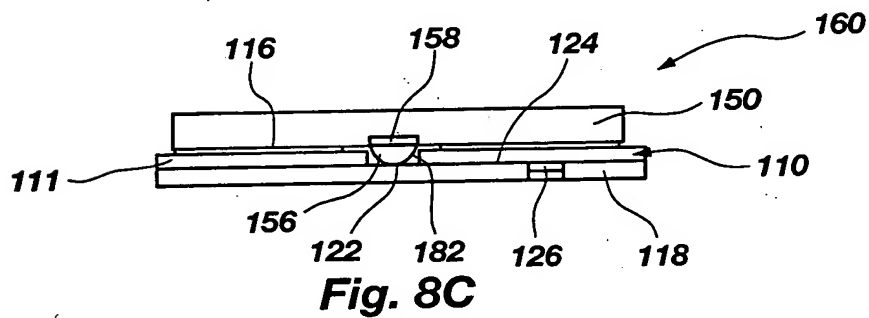
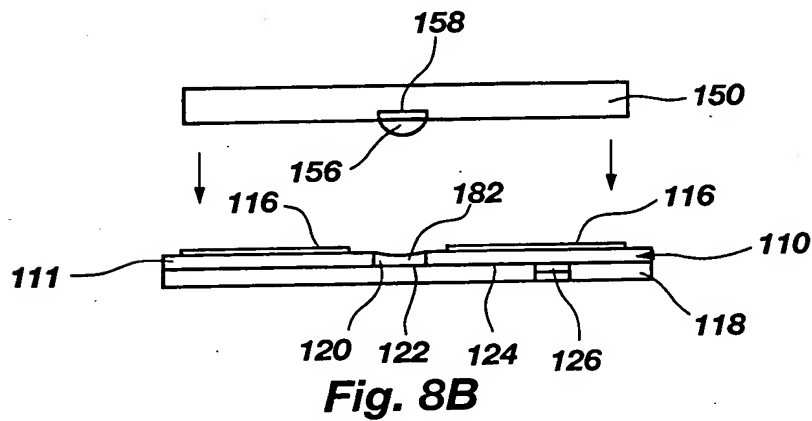
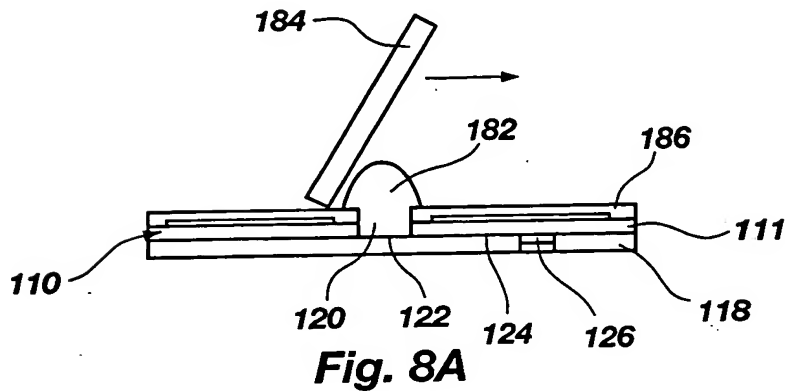


Fig. 7B

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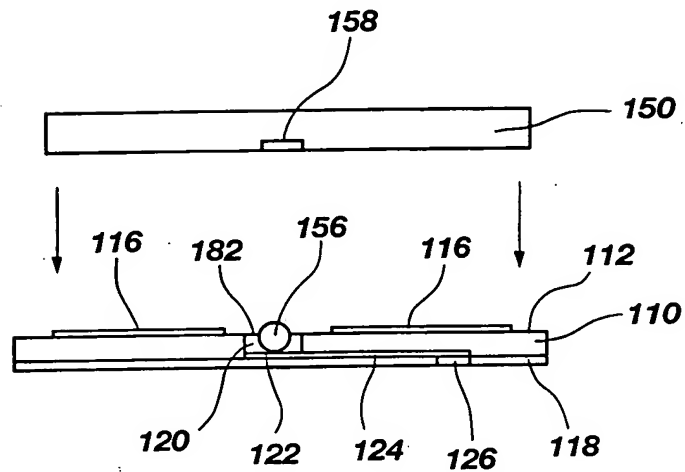


Fig. 9A

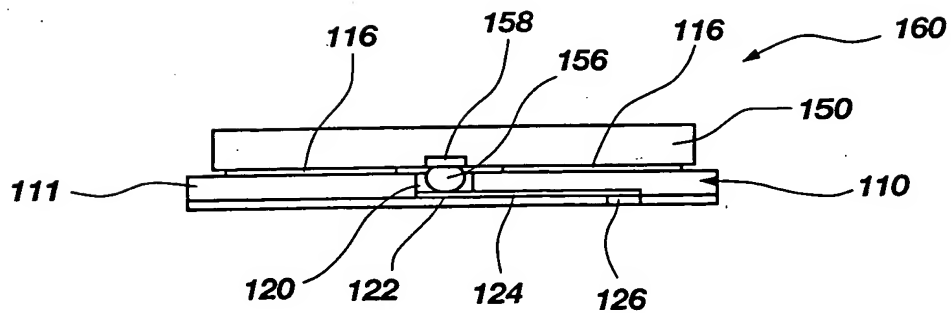


Fig. 9B

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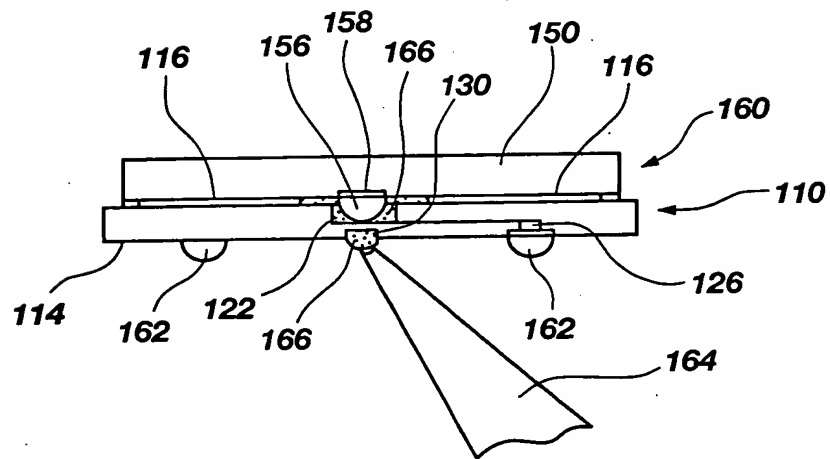


Fig. 10

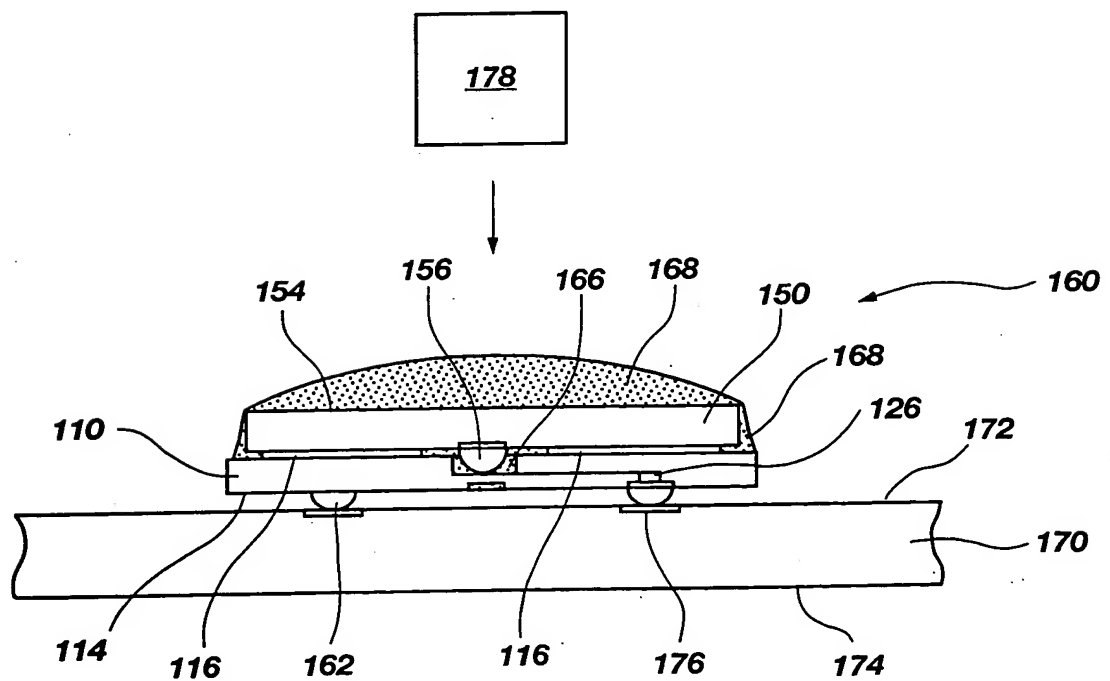


Fig. 11

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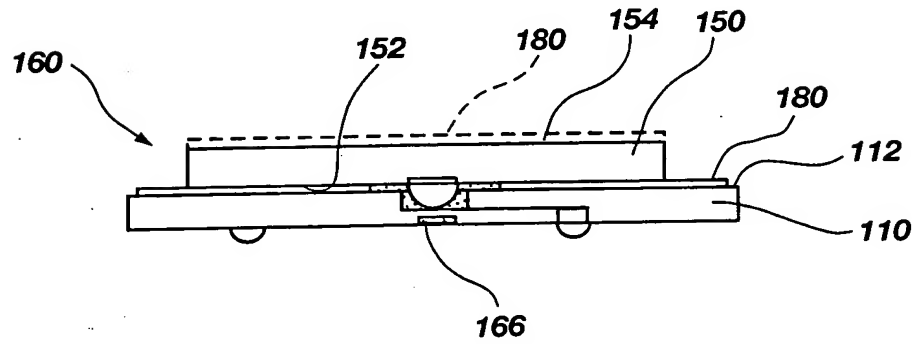


Fig. 12

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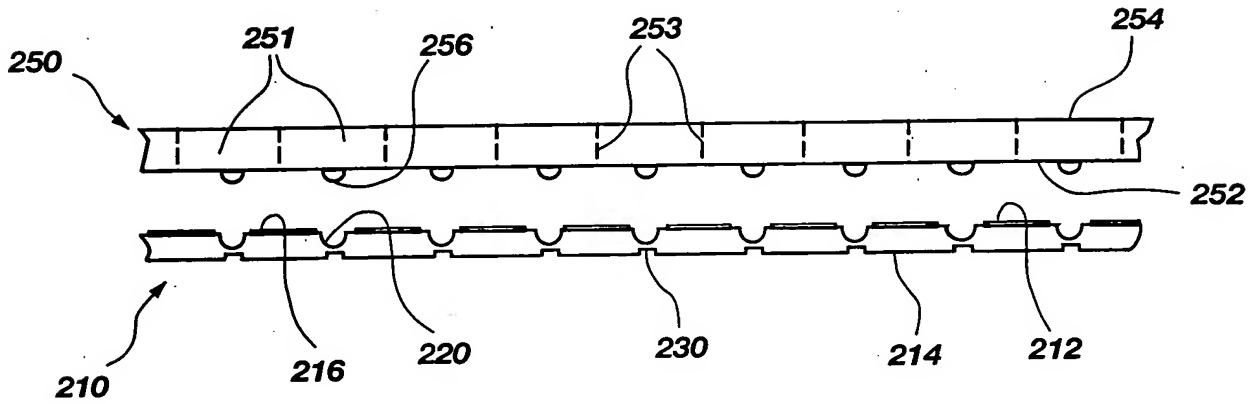


Fig. 13A

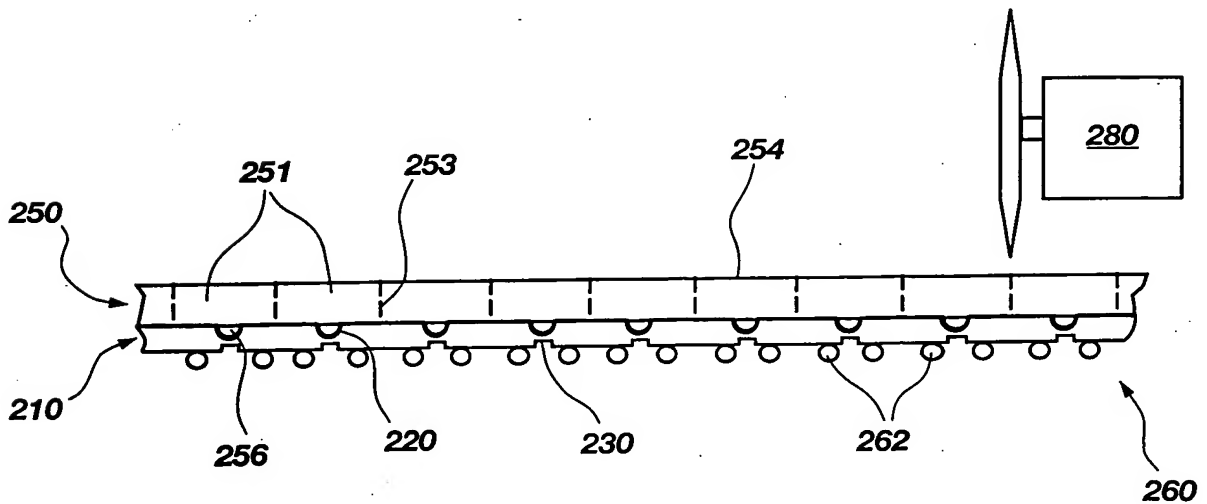


Fig. 13B

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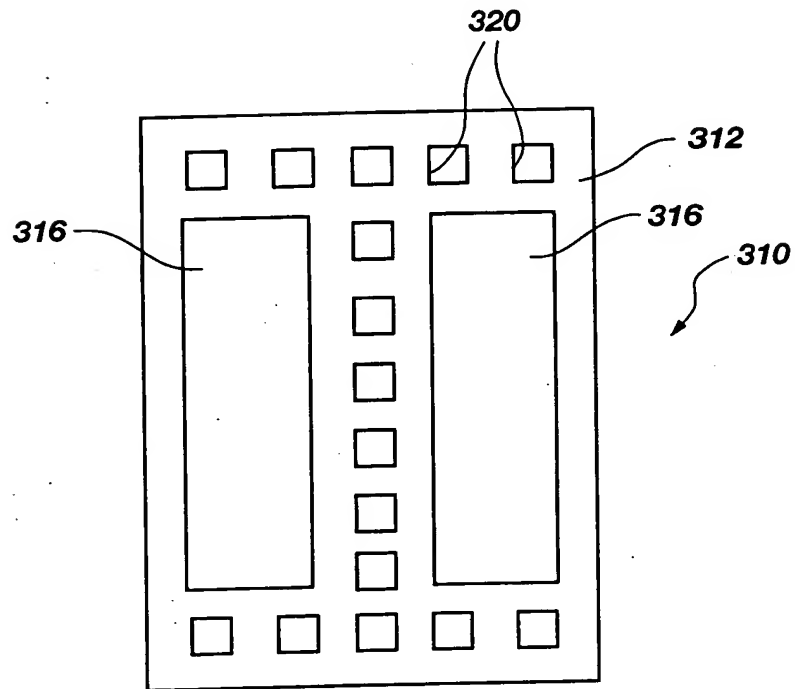


Fig. 14

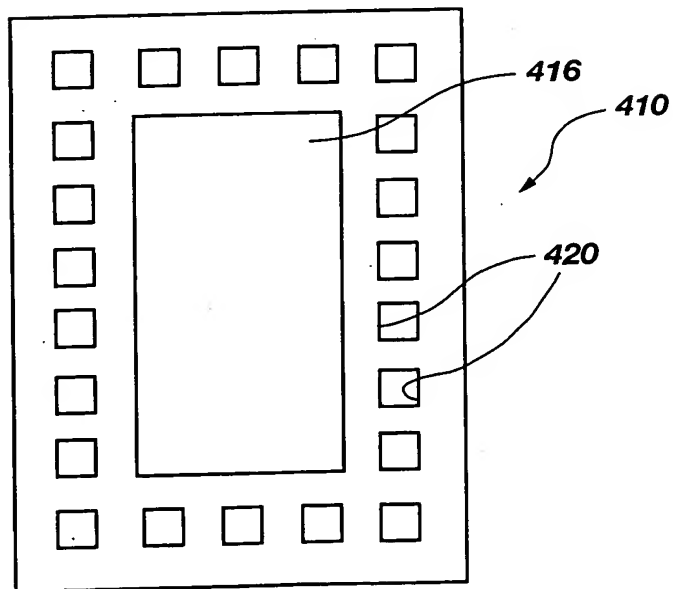


Fig. 15

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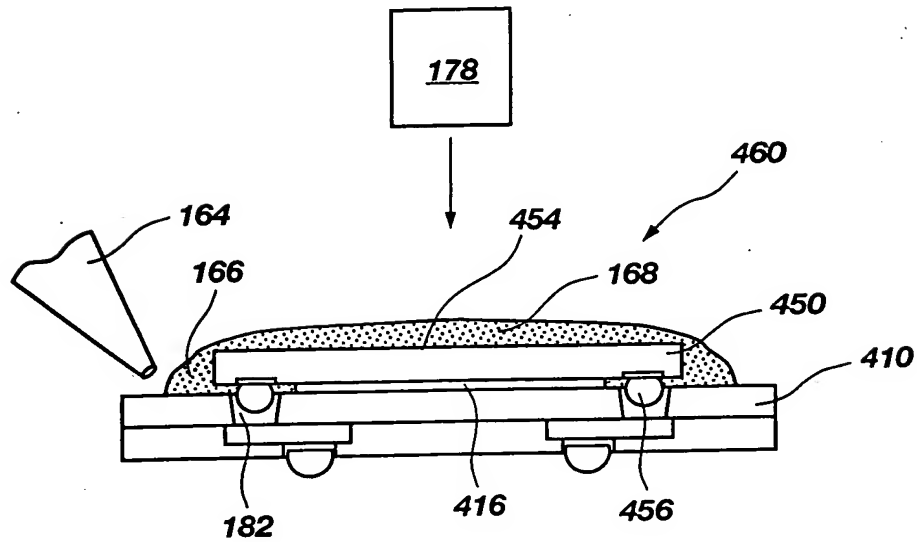


Fig. 16

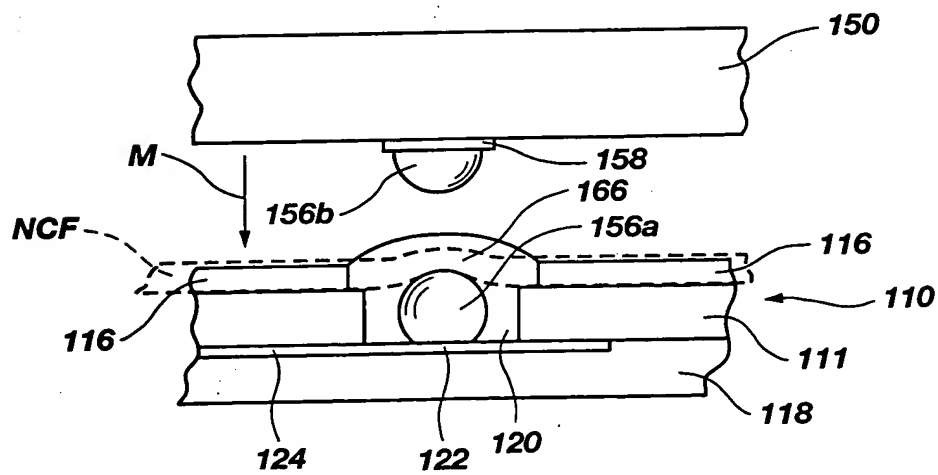


Fig. 18

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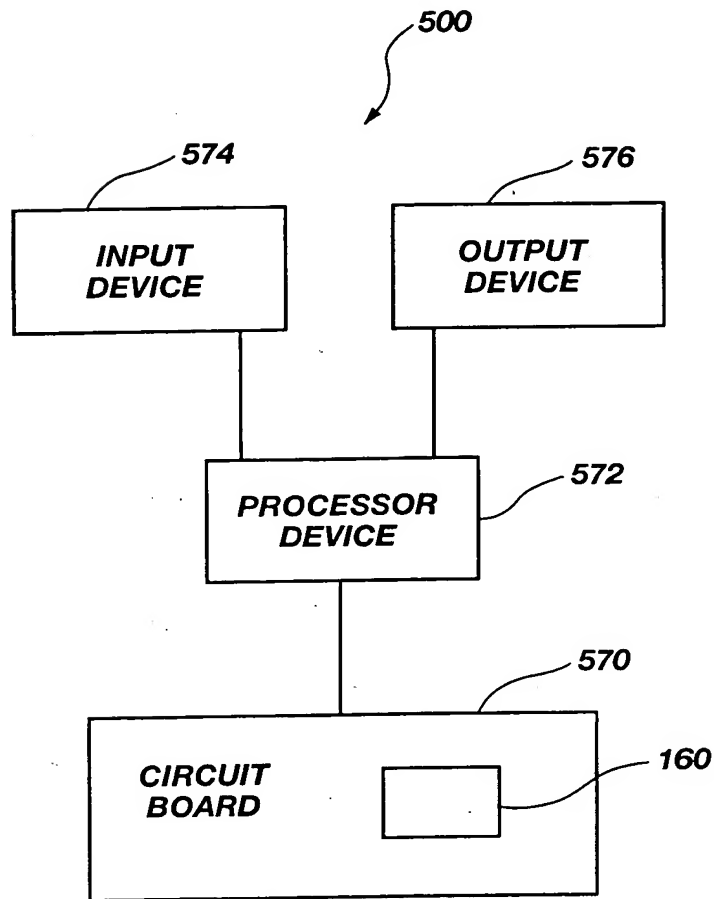


Fig. 17